DIMENSIONING AND TOLERANCING PER

CONTROLLING DIMENSION: MILLIMETERS DIMENSION 6 APPLIES TO PLATED

TERMINALS AND IS MEASURED BETWEEN

4. COPLANARITY APPLIES TO THE EXPOSED

DESIGN FEATURES TO AID IN FILLET

FORMATION ON THE LEADS DURING MOUNTING.

EXPOSED PADS CONNECTED TO DIE FLAG

PAD AS WELL AS THE TERMINALS. THIS DEVICE CONTAINS WETTABLE FLANK

USED AS TEST CONTACTS.

SIZE (0.20 X 0.25mm)

0.15 AND 0.30MM FROM THE TERMINAL TIP.

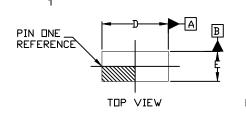
ASME Y14.5M, 1994.



DFNW12 3x1.35, 0.5P CASE 507AY **ISSUE O**

NOTES:

DATE 13 JUN 2019



DETAIL B

C-

C

SIDE VIEW

0-0

// 0.10 C

□ 0.08 C

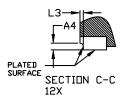
NOTE 4

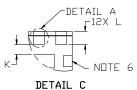


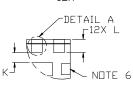
SEATING

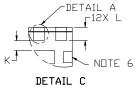
PLANE

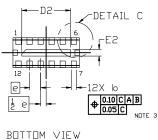
rti

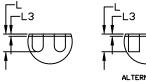


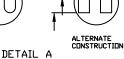


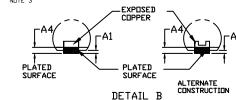












MILLIMETERS MIN. NDM. DIM MAX. 0.80 0.90 1.00 Α ---A1 0.00 0.05 0.20 REF АЗ 0.10 ___ ___ Α4 b 0.18 0.24 0.30 D 2.85 3.00 3.15 D2 2.10 2.20 2.30 1.35 1.50 Ε 1.20 0.20 0.30 E2 0.40 0.50 BSC e K 0.20 0.20 0.30 0.40 ı L3 ___ ___ 0.10

GENERIC MARKING DIAGRAM*



XX= Specific Device Code

= Date Code M

= Pb-Free Package

(Note: Microdot may be in either location)

*This information is generic. Please refer to device data sheet for actual part marking. Pb-Free indicator, "G" or microdot "■", may or may not be present. Some products may not follow the Generic Marking.

	- -2.35-	- 12	X 0.48
PACKAGE		_	
VE.		 	1.35 1.71
1 4	ф 0 0 (1.33 1.71
0.50 PITCH	_	-12X	0.27
RE	COMMEN	DED	
M□UNT	ING FO	JTPRINT	

For additional information on our Pb-Free strategy and soldering details, please download the IIN Seniconductor Soldering and Mounting Techniques Reference Manual, SILL DERRW.D.

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DESCRIPTION:	DFNW12 3x1.35, 0.5P		PAGE 1 OF 1	

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